



### Power Field Effect Transistor

### **GENERAL DESCRIPTION**

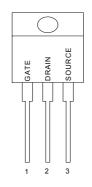
This high voltage MOSFET uses an advanced termination scheme to provide enhanced voltage-blocking capability without degrading performance over time. In addition, this advanced MOSFET is designed to withstand high energy in avalanche and commutation modes. The new energy efficient design also offers a drain-to-source diode with a fast recovery time. Designed for high voltage, high speed switching applications in power supplies, converters and PWM motor controls, these devices are particularly well suited for bridge circuits where diode speed and commutating safe operating areas are critical and offer additional and safety margin against unexpected voltage transients.

### **FEATURES**

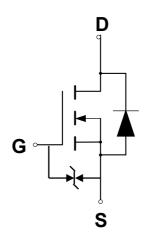
- Robust High Voltage Termination
- Avalanche Energy Specified
- ◆ Source-to-Drain Diode Recovery Time Comparable to a Discrete Fast Recovery Diode
  - Diode is Characterized for Use in Bridge Circuits
- I<sub>DSS</sub> and V<sub>DS</sub>(on) Specified at Elevated Temperature

#### PIN CONFIGURATION

TO220/TO-220F Top View



### **SYMBOL**



N-Channel MOSFET

### **ABSOLUTE MAXIMUM RATINGS**

Rating		Value	Unit
Drain to Current — Continuous		11.6	Α
- Pulsed	I <sub>DM</sub>	34.8	
Gate-to-Source Voltage — Continue	$V_{GS}$	±30	V
Total Power Dissipation – TO220	P <sub>D</sub>	175	W
– TO220FP		46	
Derate above 25℃ – TO220		1.4	W/°C
– TO220FP		0.38	
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to 150	$^{\circ}\mathbb{C}$
Single Pulse Drain-to-Source Avalanche Energy $-T_J = 25^{\circ}C$	E <sub>AS</sub>	500	mJ
$(V_{DD} = 100V, V_{GS} = 10V, I_L = 10A, L = 10mH, R_G = 25\Omega)$			
Thermal Resistance — Junction to Case -TO220		0.7	°C <b>W</b>
<ul> <li>Junction to Case -TO220FP</li> </ul>		3.8	
<ul> <li>Junction to Ambient -TO220, TO220FP</li> </ul>	$\theta_{JA}$	62.5	
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	TL	260	$^{\circ}\!\mathbb{C}$
ESD SENSITIVITY — HBM. C=100pF. R=1.5kΩ	Vesd	2000	V





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### **ORDERING INFORMATION**

Part Number	Package
GPT12N45GN220*	TO-220
GPT12N45DGN220FP*	TO-220F

<sup>\*</sup>Note: G: Suffix for PB Free Product

### **ELECTRICAL CHARACTERISTICS**

Unless otherwise specified,  $T_J = 25^{\circ}C$ .

				GPT12N45	5	
Chai	racteristic	Symbol	Min	Тур	Max	Units
Drain-Source Breakdown Voltage		V <sub>(BR)DSS</sub>	450			V
$(V_{GS} = 0 \text{ V}, I_D = 250 \ \mu \text{ A})$						
Drain-Source Leakage Current		I <sub>DSS</sub>			1	μA
$(V_{DS} = 450 \text{ V}, V_{GS} = 0 \text{ V})$						
Gate-Source Leakage Current-Fo	orward	$I_{GSSF}$			100	nA
$(V_{gsf} = 30 \text{ V}, V_{DS} = 0 \text{ V})$						
Gate-Source Leakage Current-Re	Gate-Source Leakage Current-Reverse				100	nA
$(V_{gsr} = -30 \text{ V}, V_{DS} = 0 \text{ V})$						
Gate Threshold Voltage		$V_{GS(th)}$	3	4	5	V
$(V_{DS} = V_{GS}, I_{D} = 250 \ \mu A)$						
Static Drain-Source On-Resistance (V <sub>GS</sub> = 10 V, I <sub>D</sub> = 6A) *		R <sub>DS(on)</sub>		0.49	0.6	Ω
Forward Transconductance (V <sub>DS</sub> = 15 V, I <sub>D</sub> = 6A) *		<b>g</b> fs		9		S
Input Capacitance	$(V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$	C <sub>iss</sub>		1590		pF
Output Capacitance	$(V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0  MHz)	Coss		169		pF
Reverse Transfer Capacitance		$C_{rss}$		7.87		pF
Turn-On Delay Time		t <sub>d(on)</sub>		25.6		ns
Rise Time	$(V_{DD}$ = 225 V, $I_{D}$ = 12 A, $R_{G}$ = 25 $\Omega$ ) *	t <sub>r</sub>		24.53		ns
Turn-Off Delay Time		$t_{d(off)}$		45.1		ns
Fall Time		t <sub>f</sub>		27.2		ns
Total Gate Charge	$(V_{DS} = 360 \text{ V}, I_D = 12 \text{ A}, V_{GS} = 10 \text{ V})^*$	$Q_g$		30.3		nC
Gate-Source Charge		$Q_gs$		8.43		nC
Gate-Drain Charge	VGS - 10 V)	$Q_gd$		10.3		nC
SOURCE-DRAIN DIODE CHARA	ACTERISTICS					
Forward On-Voltage(1)	$(I_S = 12 \text{ A}, V_{GS} = 0 \text{ V},$ $d_{IS}/d_t = 100\text{A/µs})$	$V_{SD}$			1.5	V
Forward Turn-On Time		t <sub>on</sub>		**		ns
Reverse Recovery Time	u <sub>IS</sub> /u <sub>t</sub> – 100Α/μs)	t <sub>rr</sub>		384		ns

<sup>\*</sup> Pulse Test: Pulse Width  $\leq$ 300 $\mu$ s, Duty Cycle  $\leq$ 2%

<sup>\*\*</sup> Negligible, Dominated by circuit inductance



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### TYPICAL ELECTRICAL CHARACTERISTICS

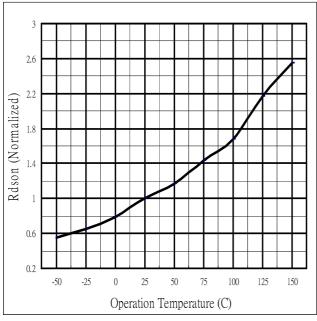


Fig 1. On-Resistance Variation with vs. Temperature

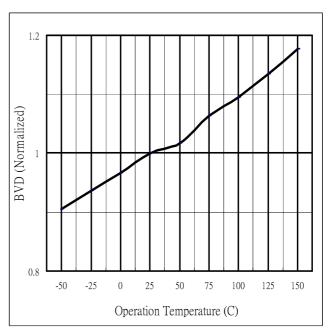


Fig.2 Breakdown Voltage Variation vs. Temperature

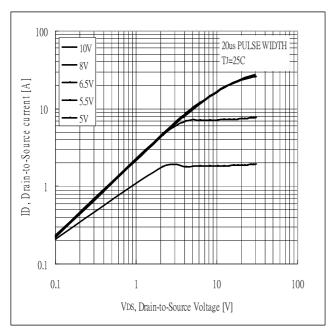


Fig 3. Typical Output Characteristics

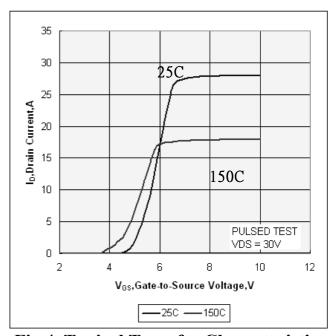


Fig 4. Typical Transfer Characteristics





# POWER FIELD EFFECT TRANSISTOR

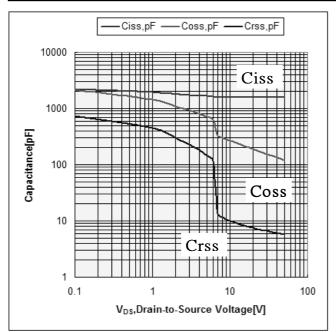


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

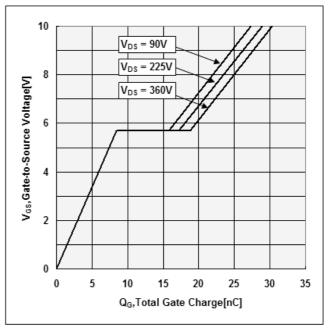


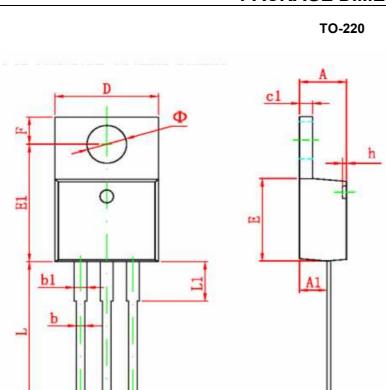
Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage





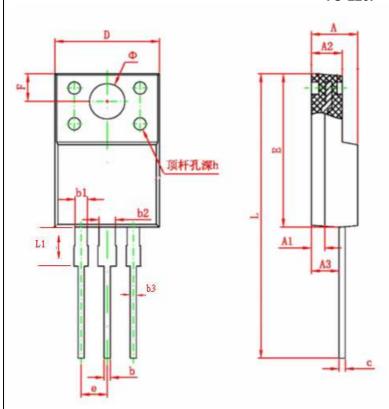
Power Field Effect Transistor

### **PACKAGE DIMENSION**



Crossk al	Dimensions In Millimeters		
Symbol	Min.	Max	
Α	4.40	4.80	
A1	2.10	2.84	
Ъ	0.71	0.91	
b1	1.17	1.37	
С	0.30	0.60	
c1	1.17	1.47	
D	9.40	10.60	
Е	8.40	9.60	
е	2.54 TYP.		
e1	4.90	5.60	
F	3.00 REF.		
Φ	3.50 REF.		
h	0.00	0.30	
L	12.50	14.00	
L1	3.50	4.00	

#### **TO-220F**



C1 -1	Dimensions In Millimeters		
Symbol	Min.	Max	
Α	3.80	4.70	
A1	1.3 REF.		
A2	2.20	3.20	
A3	2.10	3,20	
ь	0.30	0.95	
bl	1.00	1.75	
b2	1.00	1.75	
b3	0.50	0.80	
С	0.30	0.90	
D	9.90	10.40	
E	14.60	16.20	
е	2.54 TYP.		
F	3.00 REF.		
Φ	3.50 REF.		
h	0.00	0.30	
L	28.00	30.00	
L1	3,20	3.55	





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#### **IMPORTANT NOTICE**

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